

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) Use of pale or transparent particulate semiconductor materials or particulate substrates coated with pale or transparent semiconductor materials for curing and/or drying and/or for increasing the thermal conductivity of surface-coating layers and printing inks.
2. (Original) Use of semiconductor materials according to Claim 1, characterised in that the semiconductor materials are built up homogeneously from pale or transparent semiconductor materials or are applied as coating to a particulate substrate.
3. (Currently Amended) Use of semiconductor materials according to Claim 1 ~~or 2~~, characterised in that the particulate semiconductor materials and particulate substrates are spherical, flake-form or needle-shaped materials or substrates.
4. (Currently Amended) Use of semiconductor materials according to claim 1 ~~one of Claims 1 to 3~~, characterised in that the semiconductor material is built up oxidically or sulfidically.
5. (Currently Amended) Use of semiconductor materials according to claim 1 ~~one of Claims 1 to 4~~, characterised in that the semiconductor material is built up on the basis of indium oxide, antimony oxide, tin oxide, zinc oxide, zinc sulfide, tin sulfide or is a mixture of the said materials.
6. (Original) Use of semiconductor materials according to Claim 5, characterised in that the mixture is indium-tin oxide (ITO).
7. (Currently Amended) Use of semiconductor materials according to claim 1 ~~one of Claims 1 to 6~~, characterised in that the substrate is selected from the group consisting of mica flakes, SiO_2 flakes, Al_2O_3 flakes, glass flakes, aluminium flakes, BiOCl flakes, SiO_2 spheres, glass spheres, hollow glass spheres, TiO_2 spheres, polymer spheres, TiO_2 needles or mixtures thereof.

8. (Currently Amended) Use of semiconductor materials according to claim 1 ~~one of Claims 1 to 7~~, characterised in that the semiconductor materials are doped.
9. (Currently Amended) Use of semiconductor materials according to claim 1 ~~one of Claims 1 to 8~~, characterised in that the semiconductor has an amorphous, crystalline or microcrystalline structure.
10. (Original) Formulations, characterised in that they comprise one or more pale or transparent particulate semiconductor materials or particulate substrates coated with pale or transparent semiconductor materials as curing and/or drying additives.
11. (Original) Formulations according to Claim 10, characterised in that they are surface coatings or printing inks comprising semiconductor materials.